

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Kuo-Cheng Ching</td><td>01/14/2009</td></tr><tr><td>Kuo-Chi Tu</td><td>01/14/2009</td></tr><tr><td>Chun-Yao Chen</td><td>01/14/2009</td></tr></tbody></table>		Name	Execution Date	Kuo-Cheng Ching	01/14/2009	Kuo-Chi Tu	01/14/2009	Chun-Yao Chen	01/14/2009
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Kuo-Cheng Ching	01/14/2009								
Kuo-Chi Tu	01/14/2009								
Chun-Yao Chen	01/14/2009								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Road 6								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12397948</td></tr></tbody></table>		Property Type	Number	Application Number:	12397948				
Property Type	Number								
Application Number:	12397948								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	Liem T. Do								
Total Attachments: 2 source=1193_Assignment#page1.tif									

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PATENT
REEL: 022345 FRAME: 0713

Docket No.: 2008-0661 / 24061.1193
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Kuo-Cheng Ching | of | 5F, No. 8-3, Guangming 9th Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (2) | Kuo-Chi Tu | of | No. 51, Lane 550, Sec. 1, Wufu Road
Hsin-Chu 300, Taiwan, R.O.C. |
| (3) | Chun-Yao Chen | of | 3F, No. 80, Hsin-Juang Street
Hsin-Chu 300, Taiwan, R.O.C. |

have invented certain improvements in

METAL-INSULATOR-METAL STRUCTURE FOR SYSTEM-ON-CHIP TECHNOLOGY

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on 3-4-09 and assigned application number 12/397,948 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Kuo-Cheng Ching

Residence Address: 5F, No. 8-3, Guangming 9th Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: Jan 14, 2009

Kuo - Cheng Ching
Inventor Signature

Inventor Name: Kuo-Chi Tu

Residence Address: No. 51, Lane 550, Sec. 1, Wufu Road
Hsin-Chu 300, Taiwan, R.O.C.

Dated: Jan 14, 2009

Kuo - Chi Tu
Inventor Signature

Inventor Name: Chun-Yao Chen

Residence Address: 3F, No. 80, Hsin-Juang Street
Hsin-Chu 300, Taiwan, R.O.C.

Dated: Jan. 14, 2009

Chun - Yao Chen
Inventor Signature